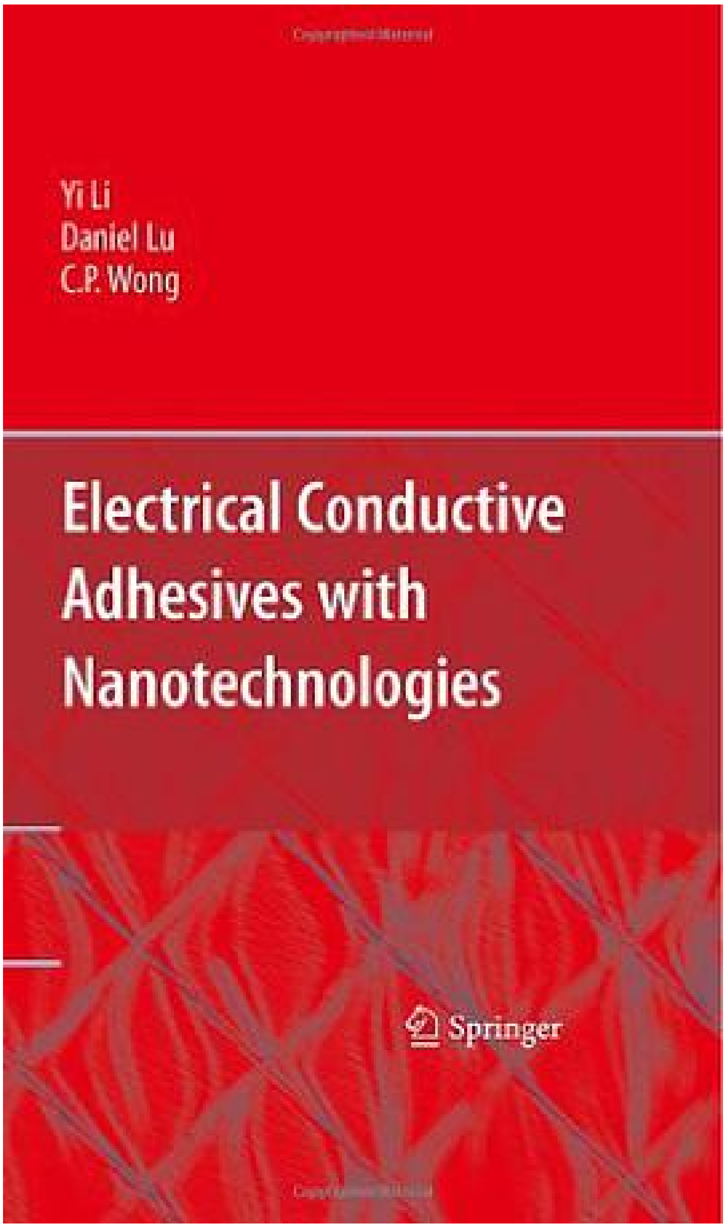
Electrical Conductive Adhesives with Nanotechnologies



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"Electrical Conductive Adhesives with Nanotechnologies" begins with an overview of electronic packaging and discusses the various adhesives options currently available, including lead-free solder and ECAs (Electrically Conductive Adhesives). The material presented focuses on the three ECA categories specifically, Isotropically Conductive Adhesives (ICAs) Anisotropically Conductive Adhesives/Films (ACA/ACF) and Nonconductive Adhesives/Films (NCA/NCF). Discussing the advantages and limitations of each technique, and how each technique is currently applied. Lastly, a detailed presentation of how nano techniques can be applied to conductive adhesives is discussed, including recent research and development of nano component adhesives/nano component films, their electrical properties, thermal performance, bonding pressure and assembly and reliability.

作者介绍:

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标签

评论

书评
